

# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	800	<b>V</b>
RMS Reverse Voltage	V <sub>R(RMS)</sub>	560	V
Average Rectified Output Current @ T <sub>A</sub> = +25°C	lo	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	55	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 7)	$R_{\theta JT}$	23	°C/W
Typical Thermal Resistance, Junction to Air (Note 7)	$R_{\theta JA}$	82	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C

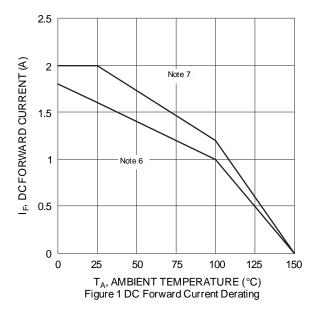
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

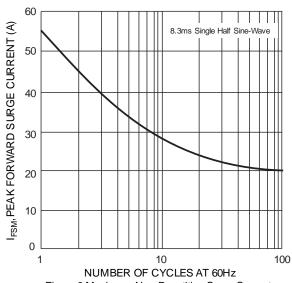
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	800	_		V	$I_R = 10\mu A$
Forward Voltage	V <sub>F</sub>		0.90 0.78 0.95 0.84	1.0 — 1.1 —		I <sub>F</sub> = 1A, T <sub>J</sub> = +25°C I <sub>F</sub> = 1A, T <sub>J</sub> = +125°C I <sub>F</sub> = 2A, T <sub>J</sub> = +25°C I <sub>F</sub> = 2A, T <sub>J</sub> = +125°C
Reverse Leakage Current (Note 5)	I <sub>R</sub>		0.12 0.005	5 —	μA mA	V <sub>R</sub> = 800V, T <sub>J</sub> = +25°C V <sub>R</sub> = 800V, T <sub>J</sub> = +125°C
Total Capacitance	Ст	_	8		pf	$V_R = 4V_{DC}$ , $f = 1MHz$

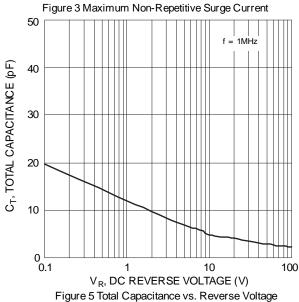
Notes:

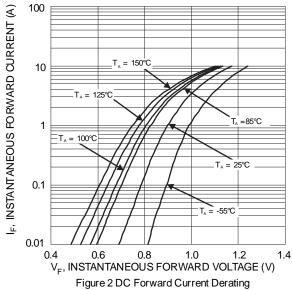
- 5. Short duration pulse test used to minimize self-heating effect.
  6. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.1" x 0.15" copper pads.
  7. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pads.

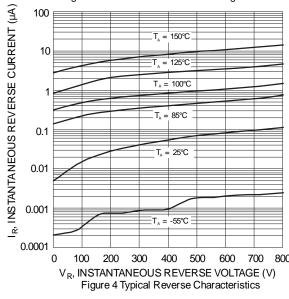


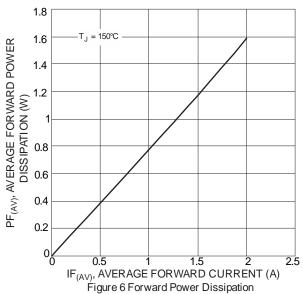










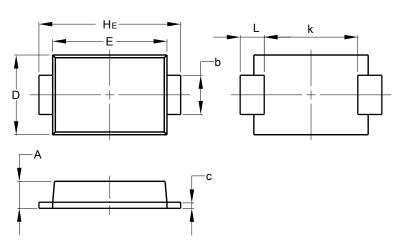




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### D-FLAT

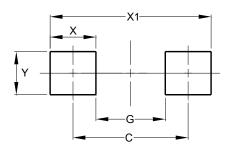


D-FLAT				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
С	0.10	0.40		
D	2.25	2.95		
Е	3.95	4.60		
k	2.80	_		
HE	5.00	5.60		
L	0.50	1.30		
All Dimensions in mm				

## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

### **D-FLAT**



Dimensions	Value (in mm)
C	4.65
G	2.80
Х	1.85
X1	6.50
Y	1.70



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